

## PSMA Announces APEC 2018 Industry Session on 3D Power Packaging

*Session to feature seven invited experts from industry and research who will present current and future component, reliability and manufacturing innovations for 3D power packaging*

MENDHAM, N.J.—January 30, 2018—[The Power Sources Manufacturers Association](#) (PSMA) Packaging Committee is sponsoring an Industry Session at [APEC 2018](#) titled, “Innovative Component, Reliability and Manufacturing Innovations for 3D Power Packaging.” Featuring speakers from leading industry and research organizations, the session ([IS14](#)) will present an up-to-date look at current and future component and manufacturing technologies utilizing high-density 3D packaging. The PSMA-sponsored session will take place on Wednesday afternoon, March 7<sup>th</sup>, 2018, from 2:00 - 5:25 p.m. in Room 212 of the Henry B. Gonzales Convention Center in San Antonio, Texas.

With the power supply industry continually being challenged to increase power density while lowering cost, companies are turning to 3D packaging technologies for additional solutions. A 3D packaging approach using embedded components (actives and passives) combined with advanced manufacturing technologies is proving to be the most reliable solution, offering the fastest time to market for achieving increased power density in a smaller footprint. This solution is already in production in semiconductor, component and power supply designs.

The [3D Power Packaging Industry Session](#) will feature seven invited experts to provide attendees with an overview of reliability concerns, component technologies and manufacturing solutions essential for successful implementation. They will also offer insights to help attendees identify potential opportunities for their companies, and to explore the potential of applying this emerging technology to meet their market demands.

Co-chairs of the session, Ernie Parker of Crane Aerospace & Electronics and Brian Narveson of Narveson Consulting, encourage industry professionals to attend the Industry Session on 3D power packaging. Parker stated: “This speaker session will provide a valuable opportunity for attendees to meet other professionals who are active in the evolving design, reliability and manufacturing of 3D embedded components in sub-assembly and power supply designs.” Narveson added: “We encourage everyone to register for APEC 2018 and to make plans to attend the 3D Power Packaging session. Participants should also consider joining the other [PSMA-sponsored meetings](#) being held throughout the week.”

### PSMA Packaging Committee Meeting Notice

All APEC attendees are invited to attend the PSMA Packaging Committee meeting scheduled for Tuesday, March 6<sup>th</sup>, 2018, from 10:00 a.m. to noon in 008B.

### About PSMA

PSMA is a non-profit professional organization with the two-fold objective of enhancing the stature and reputation of its members and their products and improving their technological power sources knowledge. Its aim is to educate the electronics industry, academia, government and industry communities as to the applications and importance of all types of power sources and conversion devices.

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